## In the Specification:

Please amend the title of the application as follows:

## METHOD AND APPARATUSES FOR FORMING A PLANARIZING PAD FOR PLANARIZATION OF MICROLECTRONIC SUBSTRATES

Please add a new section directly before "Technical Field" as follows:

## CROSS-REFERENCE TO RELATED APPLICATIONS

This application is a divisional application of U.S. Patent Application No.
09/649,429, entitled "METHOD FOR FORMING A PLANARIZING PAD FOR
PLANARIZATION OF MICROELECTRONIC SUBSTRATES," filed August 28, 2000,
now U.S. Patent No, issued; and is related to U.S. Patent
Application No [Attorney Docket No. 108298404US1], entitled
"PLANARIZING PADS FOR PLANARIZATION OF MICROELECTRONIC
SUBSTRATES," filed February 5, 2004, which is a divisional application of U.S. Patent
Application No. 09/649,429, both of which are herein incorporated by reference in their
entireties.